

Infrared LED



L12771 series

Peak emission wavelength: 1.3 μm

The L12771 series is an infrared LED using InGaAs material. Peak emission wavelength is 1.3 μ m, making the L12771 series suitable as a reference light source for detection of moisture.

- Features

- High output
- High reliability
- Compact, surface mount type package (1.6 × 0.8 × 0.7^t mm): L12771-0130G
- **■** Supports lead-free reflow soldering

- Applications

- Reference light source for moisture meter
- Light source for detecting photosensitive material

- Structure

Type no.	Package	Window material
L12771	Metal	Borosilicate glass
L12771-01	Metal	Lens type borosilicate glass
L12771-0130G	Surface mount type glass epoxy	Silicone resin

■ Absolute maximum ratings (Ta=25 °C, unless otherwise noted)

Type no.	Reverse voltage VR (V)	Forward current IF (mA)	Forward current decrease rate Ta > 25 °C (mA/°C)	Pulse forward current	Pulse forward current decrease rate Ta > 25 °C (mA/°C)	dissipation	Operating temperature Topr*2	Storage temperature Tstg* ² (°C)	Soldering temperature Tsol (°C)
L12771		,	(, - ,	, ,	, ,	,	(- /	(- /	(- /
L12771-01	1	80	1.1	1.0	13	150	-30 to +85	-40 to +100	-
L12771-0130G				0.5	6.7				250 (twice)*3

^{*1:} Pulse width=10 µs, duty ratio=1%

When there is a temperature difference between a product and the surrounding area in high humidity environments, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

► Electrical and optical characteristics (Ta=25 °C)

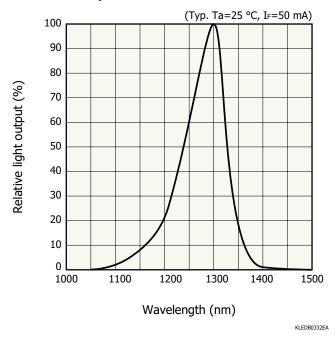
Type no.	Peak emission wavelength λp IF=50 mA		Spectral half width Δλ IF=50 mA	Radiant flux ¢c IF=50 mA		Forward voltage VF IF=50 mA		Reverse current IR VR=1V	Cutoff frequency fc*4		
	Min. (nm)	Typ. (nm)	Max. (nm)	Typ. (nm)	Min. (mW)	Typ. (mW)	Typ. (V)	Max. (V)	Max. (µA)	Min. (MHz)	Typ. (MHz)
L12771					2.0	2.8		1.5			
L12771-01	1250	1300	1350	90	2.2	3.1	1.0	1.5	10	10	15
L12771-0130G]				3.2	4.4]	1.3			

^{*4:} IF=50 mA ± 10 mAp-p, frequency at which the light output drops by 3 dB relative to the output at 100 kHz

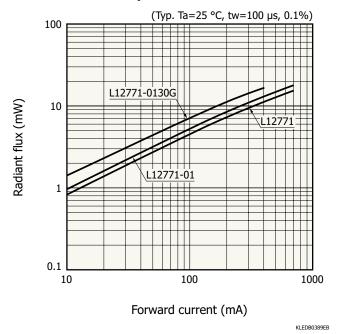
^{*2:} No dew condensation

^{*3:} Reflow soldering, JEDEC J-STD-020 MSL 2a, see P.7

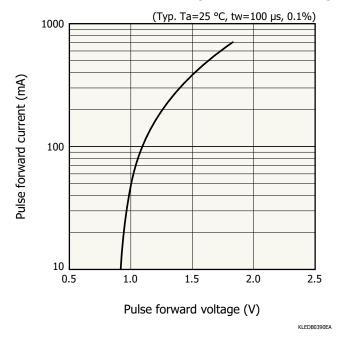
Emission spectrum



- Radiant flux vs. pulse forward current

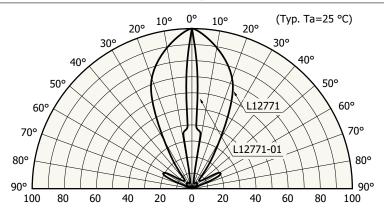


Pulse forward current vs. pulse forward voltage



Directivity

L12771/-01

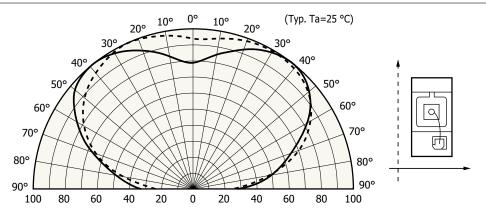


Relative light output (%)

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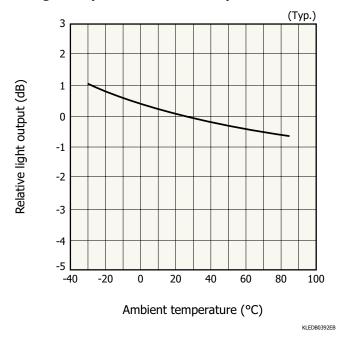
L12771-0130G

Relative light output (%)

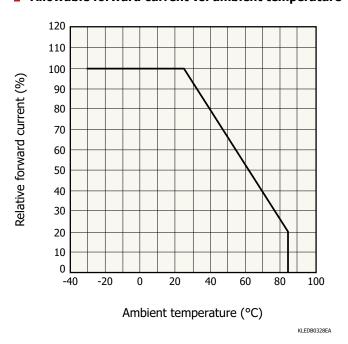


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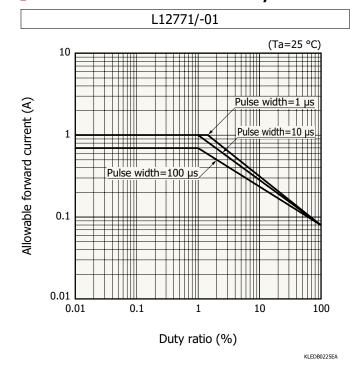
Light output vs. ambient temperature

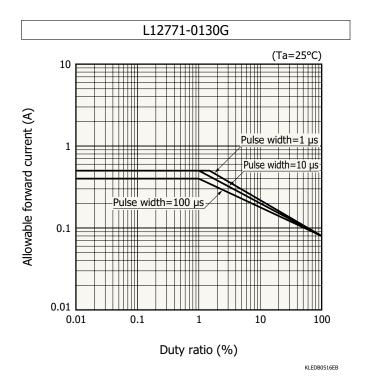


- Allowable forward current vs. ambient temperature



- Allowable forward current vs. duty ratio

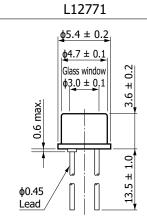


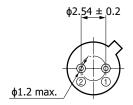


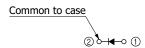
Infrared LED

L12771 series

Dimensional outlines (unit: mm)







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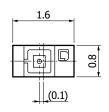
#6.5

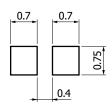
KLEDA0103EB

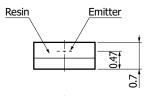
KLEDA0092EB

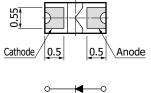
L12771-0130G

Recommended land pattern









Electrode
Chip position accuracy
with respect to package center
-0.25≤X≤+0.05
-0.15≤Y≤+0.15
Tolerance unless otherwise noted: ±0.1
Standard packing state:
reel (2000 pcs/roll)

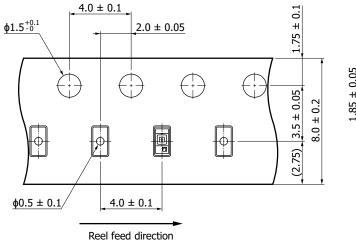
KLEDA0107EB

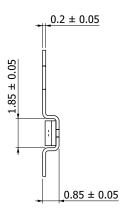
Standard packing specifications (L12771-0130G)

■ Reel (conforms to JEITA ET-7200)

Outer diameter	Hub diameter	Tape width	Material	Electrostatic characteristics
ф180 mm	ф60 mm	8 mm	PS	Conductive

■ Embossed tape (unit: mm, material: PS, conductive)





0.9 ± 0.05

KLEDC0063EA

- Packing quantity 2000 pcs/reel
- Packing stage
 Reel and desiccant in moisture-proof packaging (vaccum-sealed)

Recommended soldering conditions

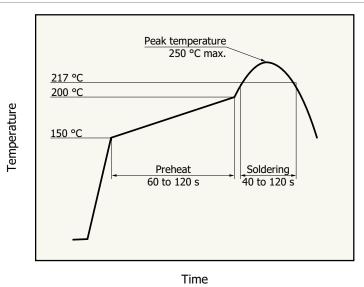
L12771/-01

· Solder temperature: 260 °C (5 s or less, once)

Solder the leads at a point at least 1 mm away from the package body.

Note: When you set soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

L12771-0130G



- After unpacking, store the device in an environment at a temperature range of 5 to 30 °C and a humidity of 60% or less, and perform reflow soldering within 4 weeks.
- The effect that the product receives during reflow soldering varies depending on the circuit board and reflow oven that are used. When you set reflow soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

KLEDB0536EC

Baking (L12771-0130G)

If more than 12 months have passed in the unopend state or storage conditions are exceeded after opening the package, baking is required to remove moisture before reflow soldering. For the baking, refer to "Precautions / Surface mount type products" in the related information.

- Recommended baking conditions
- · Temperature: 150 °C (3 hours, once)

Note: When you set baking conditions, check that problems do not occur in the product by testing out the conditions in advance.

Infrared LED

L12771 series

Related information

www.hamamatsu.com/sp/ssd/doc_en.html

- Precautions
- Disclaimer
- · Safety consideration / Opto-semiconductors
- · Precautions / Surface mount type products
- · Precautions / Compound opto-semiconductors (photosensors, light emitters)
- Catalogs
- · Selection guide / LED
- · Technical note / LED

Information described in this material is current as of November 2024.

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